

ABSTRACT OF THE DISCLOSURE

In the present invention, at the time of bonding a top plate with an ink supply member pre-bonded thereto to one side of a head substrate directly or indirectly through a thermosetting adhesive to close grooves formed in the head substrate, or at the time of later bonding an ink supply member through a thermosetting adhesive to a top plate which has been bonded directly or indirectly to a head substrate, the bonding is carried out while applying to the head substrate and the top plate such a load as maintains the head substrate and the top plate in parallel with each other after curing of the adhesive. Therefore, even if the thermal expansion coefficient of the ink supply member is higher than that of the head substrate or even if the thermal expansion coefficients of both ink supply member and top plate are higher than the thermal expansion coefficient of the head substrate, it is possible to prevent warping of the head substrate and the top plate at the time of curing of the thermosetting adhesive and hence possible to facilitate aligning of nozzles.